

**Qualification Plan:**

Estimated date for qualification completion: 13 November 2015

IC Reliability Plan**1.0****REFERENCE DOCUMENTS:** 12MSB17722C - Product Reliability Qualification Process Specification**2.0****WLP/FLIP Reliability Plan**

Fab site change from Gunma, Japan to Niigata, Japan

3.0

Package	WLCSP179 WLCSP36 WLFCP6	Wafer Fab Site	Niigata
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4.0**RELIABILITY TESTING REQUIREMENTS**

Test	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
HTOL	TJ ~ 150°C, for 1008 hrs	Test @ Room	77	3	231	
HTSL	150°C for 1008 hrs	Test @ Room	77	3	231	
THB	85°C/85% RH for 1008 hrs	Test @ Room	77	3	231	
TC	-40°C to +125°C for 500 cycles	Test @ Room	77	3	231	

Samples should be available after completion of Qualification.

List of affected Standard Parts:

LV52130A0XA-VH
 LV52130A4XA-VH
 LV52130N0XA-VH
 LV52130N4XA-VH
 LV52207NXA-VH
 LV52207XA-VH